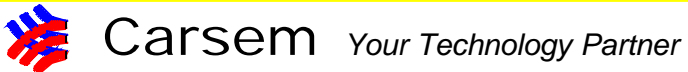
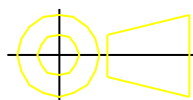


FOR REVISION UPDATE PLEASE REFER TO HISTORY OF CHANGES.



REV  
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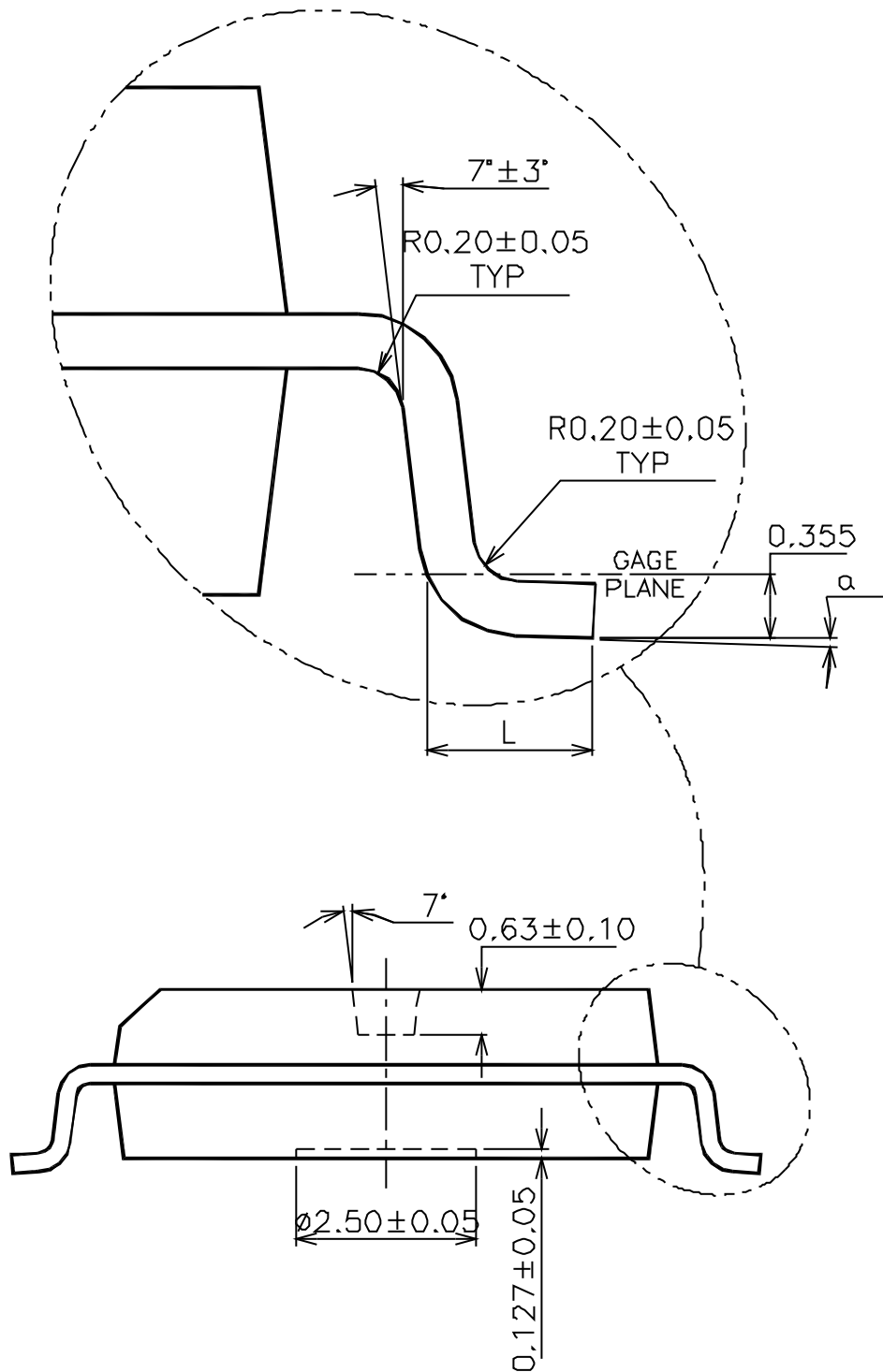
DWG NO: PKGQS0002	
APP'D	KH LEE
CHECKED	ARAVEN
DESIGNED	ARAVEN
DRAWN	KHALIM




FILE: \PKGQS0002

QSOP  
PACKAGE OUTLINE

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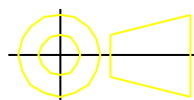


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DWG NO: PKGQS0002	
APP'D	KH LEE
CHECKED	ARAVEN
DESIGNED	ARAVEN
DRAWN	KHALIM



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DIM	QSOP 36LD(SSOP)		NOTE	QSOP 44LD		NOTE
	MIN	MAX		MIN	MAX	
A	2.44	2.64		2.44	2.64	
A1	0.10	0.30		0.10	0.30	
B	0.28	0.51		0.28	0.51	
C	0.23	0.32		0.23	0.32	
D	15.20	15.40		17.73	17.93	
E	7.40	7.60		7.40	7.60	
E1	10.11	10.51		10.11	10.51	
L	0.40	1.27		0.40	1.27	
R	0.63	0.89		0.63	0.89	
α	0°	8°		0°	8°	
e	0.80 REF			0.80 REF		
ZD	0.85			0.51		

Note :

1. Lead coplanarity should be 0 to 0.10mm (.004") max.
2. Package surface finishing ; All sides #27~30.
3. All dimensions excluding mold flashes.
4. Max deviation of center package and center of leadframe to be 0.10mm (.004").
5. Max misalignment between top and btm center of package to be 0.10mm (.004").
6. End flash from the package body shall not exceed 0.152 (.006") per side(D).
7. Dimension B does not include dambar protrusion / intrusion and solder coverage.

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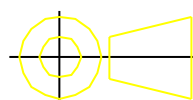


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DWG NO: PKGQS0002

APP'D	KH LEE
CHECKED	ARAVEN
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QSOP  
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